What is claimed is:

1. A solvent swell composition comprising a lactone in a sufficient amount such that the solvent swell composition conditions a resinous material upon contacting the resinous material with the solvent swell composition such that etching the conditioned resinous material provides a porous texturing of the conditioned resinous material.

2. The solvent swell composition of claim 2, wherein the lactone comprises from about 20% to about 80% bv of the solvent swell composition.

3. The solvent swell composition of claim 1, wherein the lactone comprises epsilon-caprolactone, gamma-caprolactone, gamma-valerolactone, or derivatives thereof.

4. The solvent swell composition of claim1, further comprising an amide.

5. The solvent swell composition of claim1, further comprising one or more organic solvents of ethylene glycol, diethylene glycol, triethylene glycol, polyethylene glycol, propylene glycol, dipropylene glycol, tripropylene glycol, polypropylene glycol, (C_1-C_4) glycol ethers, (C_1-C_4) glycol ether acetates, (C_1-C_{12}) alkyl acetates, ethyl lactate, ethyl butyrate, acetone, hexanone, pentanone, glyoxal, alkylene carbonates or mixtures thereof.

6. The solvent swell composition of claim 1, wherein the resinous material has a Tg of about 150° C or greater.

7. A method of treating a resinous material comprising contacting the resinous material with a solvent swell composition comprising a lactone in a sufficient amount to condition the resinous material for porous texturing with an etchant; and contacting the conditioned resinous material with an etchant to porously texturize the conditioned resinous material.

8. The method of claim 7, wherein the lactone consists of epsilon-caprolactone, gamma-caprolactone, gamma-valerolactone.

9. The method of claim 7, wherein the resinous material comprises epoxy resins, polyimide resins, cyanate ester resins, bismaleimide triazine resins, resin coated copper type materials or composites thereof.

10. The method of claim 9, wherein the Tg of the resinous material is 150° C or higher.

11. The method of claim 9, wherein the resinous material is disposed on a printed wiring board, or an inner layer thereof.

12. The method of claim 7, wherein the etching is performed with a composition comprising permanganate.

13. The method of claim 7, further comprising the step of contacting the porous texture of the resinous material with an activator such that the activator is dispersed within pores and on a surface of the resinous material.

14. The method of claim 13, wherein the activator comprises noble metals of Au, Ag, Pt, Pd, Ir, Rh, Ru, Os or mixtures thereof.

15. A method of treating a resinous material comprising contacting the resinous material with a solvent swell composition comprising a lactone consisting of epsilon-caprolactone and gamma-caprolactone in combination with an amide such that the epsilon-caprolactone or gamma-caprolactone and amide are in sufficient amounts to condition the resinous material for porous texturing with an etchant; and contacting the conditioned resinous material with an etchant.

16. The method of claim 15, further comprising the step of etching the porous textured resinous material with an etching composition comprising permanganate.

17. The method of claim 15, further comprising the step of contacting the porous textured resinous material with an activator such that the activator is dispersed within the pores and on a surface of the resinous material.

18. The method of claim 17, wherein the activator comprises a noble, non-noble metal or mixtures thereof.

19. The method of claim 17, further comprising depositing a metal within pores and on the surface of the resinous material such that a continuous metal layer is bonded to the resinous material.

20. The method of claim 15, wherein the resinous material is disposed on a printed wiring board or inner layers thereof.